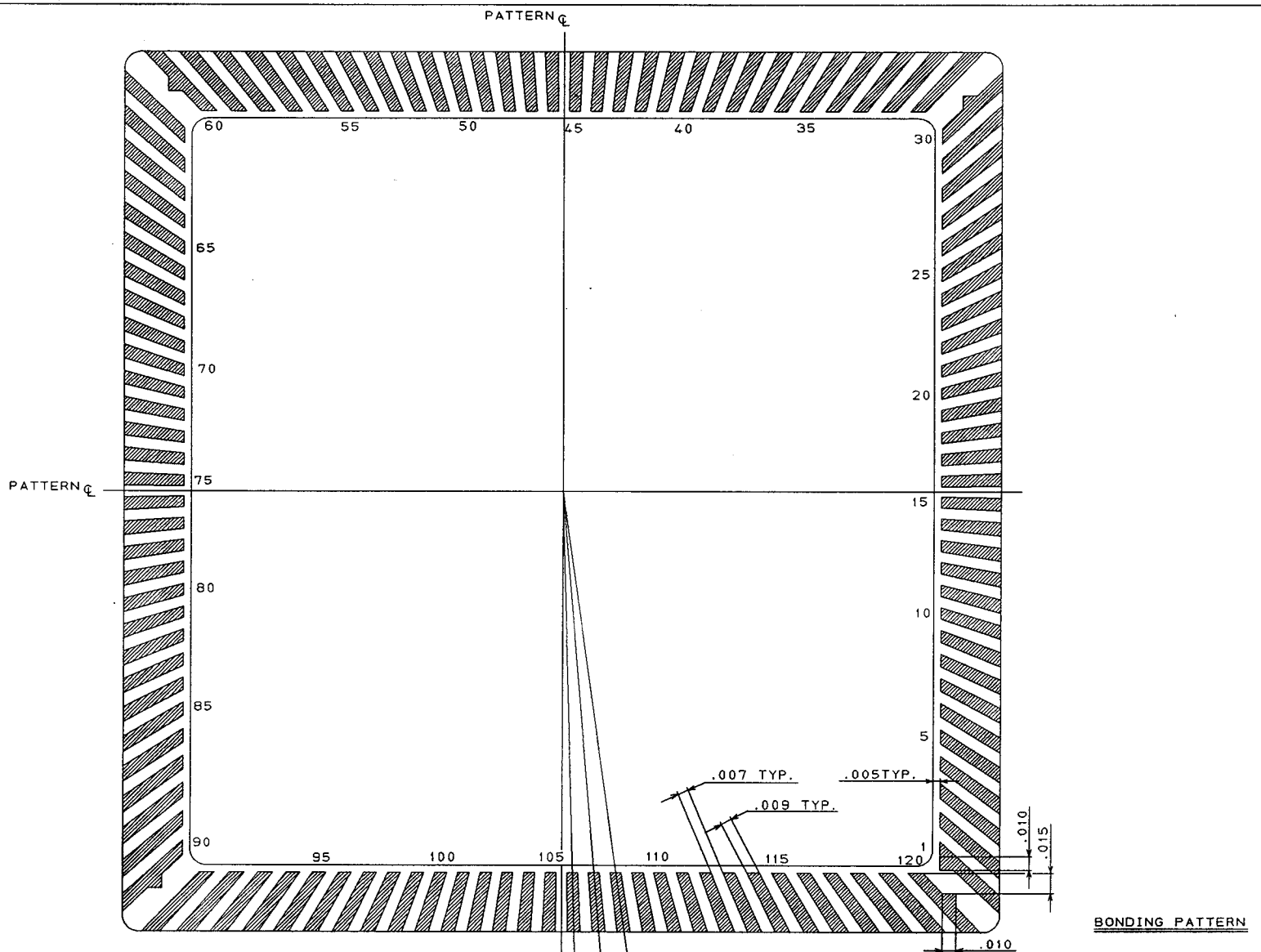


- NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. EXTRA PIN (D4) TO BE FLOATING FROM ANY PINS.
 6. LEAD RESISTANCE : 800 mΩ MAX.

					NAME 121 PIN GRID ARRAY PACKAGE		TOLERANCE UNLESS OTHERWISE SPECIFIED ± .005 THIRD ANGLE PROJECTION		DRAWN S.M		CHECKED S.A		APPROVED T.A		DATE NOV.26, '86	
MODIFICATION					SCALE 5/1		MATERIAL AS INDICATED		DRAWING NO. KD-P86A76-C		SHEET 1/8					
△ ADDED : SHEETS No.4/8~8/8 △ REDRAWN △ REDRAWN					SEP.22.'86 S.Y SHU/S.HI T.A DEC.9.'86 S.N H.S/K.M T.A 3.14.'89 N.I A.F/T.A M.K		KYOCERA KYOCERA CORPORATION KYOTO JAPAN									
CHANGED					DATE		DRAWN		CHECKED		APPROVED					



MODIFICATION						NAME 121 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE 20/1	MATERIAL	S.M	S.A	T.A	NOV.26.86
	REDRAWN	DEC.9.89	S.N	H.S/K.M	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		KD-P86A76-C	SHEET 2/8
	CHANGED		DATE	DRAWN	CHECKED			APPROVED			

